

## Advance Information

# 1.0 A 6.8 V Dual Motor Driver IC

The 17517 is a monolithic triple totem-pole-output power IC designed to be used in portable electronic applications to control small DC motors and solenoids. The 17517 can operate efficiently with supply voltages as low as 2.0 V to as high as 6.8 V. Its low  $R_{DS(ON)}$  totem-pole output MOSFETs (0.46  $\Omega$  typical) can provide continuous drive currents of 1.0 A and handle peak currents up to 3.0 A. It is easily interfaced to low-cost MCUs via parallel 3.0 V- or 5.0 V-compatible logic. The device can be pulse width modulated (PWM-ed) at up to 200 kHz.

The 17517 can drive two motors in two directions one at a time or drive one motor in two directions and one solenoid with synchronous rectification of freewheeling currents one at a time. Two-motor operation is accomplished by hooking one motor between OUTA and OUTB and hooking the other motor between OUTB and OUTC. Motor plus solenoid operation is accomplished by hooking a motor between OUTA and OUTB and a solenoid between OUTC and GND.

This device contains an integrated charge pump and level shifter (for gate drive voltages), integrated shoot-through current protection (cross-conduction suppression logic and timing), and undervoltage detection and shutdown circuitry.

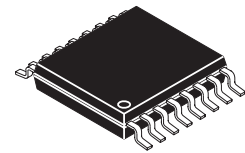
The 17517 has four operating modes: Forward, Reverse, Brake, and Tri-States (High Impedance).

### Features

- 2.0 V to 6.8 V Continuous Operation
- Output Current 1.0 A (DC), 3.0 A (Peak)
- MOSFETs < 600 m $\Omega$   $R_{DS(ON)}$  @ 25°C Guaranteed
- 3.0 V/5.0 V TTL-/CMOS-Compatible Inputs
- PWM Frequencies up to 200 kHz
- Undervoltage Shutdown

17517

1.0 A 6.8 V DUAL MOTOR DRIVER IC

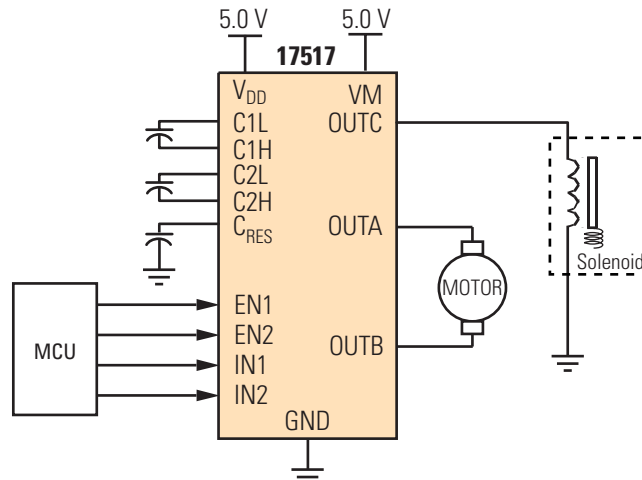


DTB SUFFIX  
CASE 948F-01  
16-LEAD TSSOP

### ORDERING INFORMATION

Device	Temperature Range (T <sub>A</sub> )	Package
MPC17517DTB/R2	-20°C to 65°C	16 TSSOP

17517 Simplified Application Diagram



This document contains certain information on a new product. Specifications and information herein are subject to change without notice.

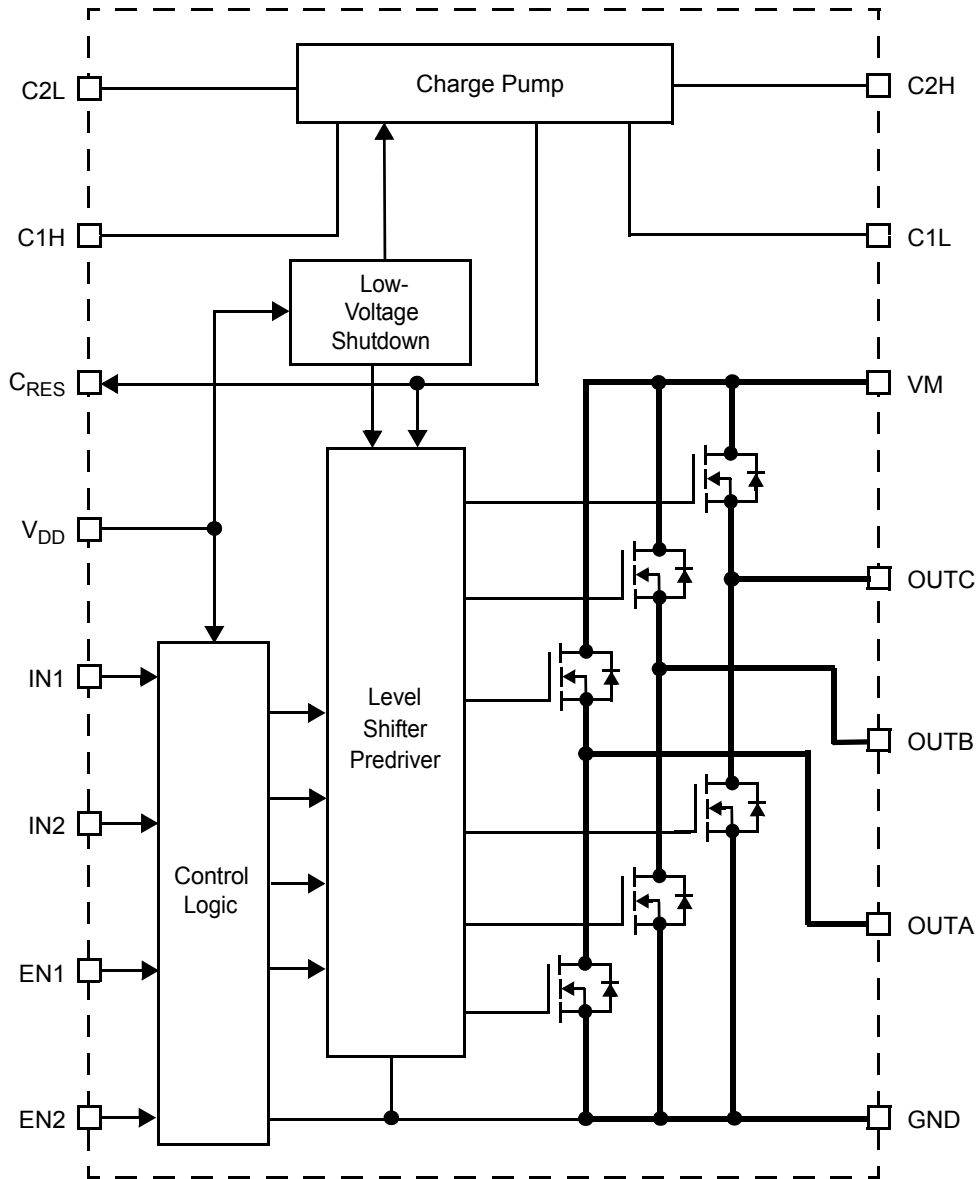
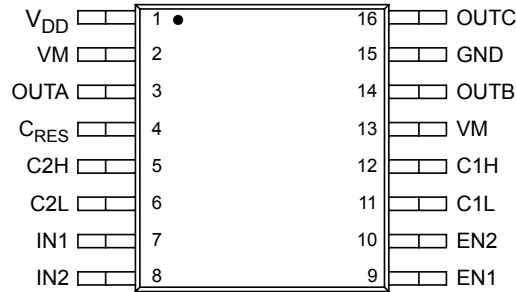


Figure 1. 17517 Simplified Internal Block Diagram



## TERMINAL FUNCTION DESCRIPTION

Terminal	Terminal Name	Formal Name	Definition
1	V <sub>DD</sub>	Control Circuit Power Supply	Positive power source connection for control circuit.
2, 13	VM	Motor Drive Power Supply	Motor power supply voltage input terminals.
3	OUTA	Output A	Driver output A terminal.
4	C <sub>RES</sub>	Charge Pump Output Capacitor Connection	Charge pump reservoir capacitor terminal.
5	C2H	Charge Pump 2H	Charge pump bucket capacitor 2 (positive pole).
6	C2L	Charge Pump 2L	Charge pump bucket capacitor 2 (negative pole).
7	IN1	Input Control 1	Control signal input 1 terminal.
8	IN2	Input Control 2	Control signal input 2 terminal.
9	EN1	Enable Control Signal Input 1	Enable control signal input 1 terminal.
10	EN2	Enable Control Signal Input 2	Enable control signal input 2 terminal.
11	C1L	Charge Pump 1L	Charge pump bucket capacitor 1 (negative pole).
12	C1H	Charge Pump 1H	Charge pump bucket capacitor 1 (positive pole).
14	OUTB	Output B	Driver output B terminal.
15	GND	Ground	Ground connection.
16	OUTC	Output C	Driver output C terminal.

## MAXIMUM RATINGS

All voltages are with respect to ground unless otherwise noted. Exceeding the ratings may cause a malfunction or permanent damage to the device.

Rating	Symbol	Value	Unit
Motor Supply Voltage	$V_M$	-0.5 to 8.0	V
Charge Pump Output Voltage	$V_{CRES}$	-0.5 to 14	V
Logic Supply Voltage	$V_{DD}$	-0.5 to 7.0	V
Signal Input Voltage	$V_{IN}$	-0.5 to $V_{DD}+0.5$	V
Driver Output Current			A
Continuous	$I_O$	1.0	
Peak (Note 1)	$I_{OPK}$	3.0	
ESD Voltage			V
Human Body Model (Note 2)	$V_{ESD1}$	±2000	
Machine Model (Note 3)	$V_{ESD2}$	±100	
Storage Temperature Range	$T_{STG}$	-65 to 150	°C
Operating Junction Temperature	$T_J$	-20 to 150	°C
Operating Ambient Temperature	$T_A$	-20 to 65	°C
Thermal Resistance (Note 4)	$R_{\theta JA}$	190	°C/W
Power Dissipation (Note 5)	$P_D$	657	mW
Soldering Temperature (Note 6)	$T_{SOLDER}$	245	°C

### Notes

- $T_A = 25^\circ\text{C}$ , 10 ms pulse width at 200 ms intervals.
- ESD1 testing is performed in accordance with the Human Body Model ( $C_{ZAP} = 100 \text{ pF}$ ,  $R_{ZAP} = 1500 \Omega$ ).
- ESD2 testing is performed in accordance with the Machine Model ( $C_{ZAP} = 200 \text{ pF}$ ,  $R_{ZAP} = 0 \Omega$ ).
- 37 mm x 50 mm Cu area (1.6 mm FR-4 PCB).
- Maximum at  $T_A = 25^\circ\text{C}$ .
- Soldering temperature limit is for 10 seconds maximum duration. Not designed for immersion soldering. Exceeding these limits may cause malfunction or permanent damage to the device.

## STATIC ELECTRICAL CHARACTERISTICS

Characteristics noted under conditions  $T_A = 25^\circ\text{C}$ ,  $V_{DD} = V_M = 5.0\text{ V}$ ,  $\text{GND} = 0\text{ V}$  unless otherwise noted. Typical values noted reflect the approximate parameter means at  $T_A = 25^\circ\text{C}$  under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
<b>POWER</b>					
Motor Supply Voltage	$V_M$	2.0	5.0	6.8	V
Logic Supply Voltage	$V_{DD}$	2.7	5.0	5.7	V
Capacitor for Charge Pump	C1, C2, C3	0.01	0.1	1.0	$\mu\text{F}$
Standby Power Supply Current					
Motor Supply Standby Current	$I_{V_{MSTBY}}$	–	–	1.0	$\mu\text{A}$
Logic Supply Standby Current (Note 7)	$I_{V_{DDSTBY}}$	–	–	1.0	mA
Operating Power Supply Current					mA
Logic Supply Current (Note 8)	$I_{V_{DD}}$	–	–	3.0	
Charge Pump Circuit Supply Current	$I_{CRES}$	–	–	0.7	
Low-Voltage Detection Circuit					V
Detection Voltage ( $V_{DD}$ ) (Note 9)	$V_{DDDET}$	1.5	2.0	2.5	
Driver Output ON Resistance (Note 10)	$R_{DS(ON)}$	–	0.46	0.60	$\Omega$

## GATE DRIVE

Gate Drive Voltage (Note 11) No Current Load	$V_{CRES}$	12	13	13.5	V
Gate Drive Ability (Internally Supplied) $I_{CRES} = -1.0\text{ mA}$	$V_{CRESload}$	10	11.2	–	V

## CONTROL LOGIC

Logic Input Voltage	$V_{IN}$	0	–	$V_{DD}$	V
Logic Input Function ( $2.7\text{ V} < V_{DD} < 5.7\text{ V}$ )					
High-Level Input Voltage	$V_{IH}$	$V_{DD} \times 0.7$	–	–	V
Low-Level Input Voltage	$V_{IL}$	–	–	$V_{DD} \times 0.3$	V
High-Level Input Current	$I_{IH}$	–	–	1.0	$\mu\text{A}$
Low-Level Input Current	$I_{IL}$	-1.0	–	–	$\mu\text{A}$

### Notes

7.  $I_{V_{DDSTBY}}$  includes current to the predriver circuit.
8.  $I_{V_{DD}}$  includes current to the predriver circuit.
9. Detection voltage is defined as when the output becomes high-impedance after  $V_{DD}$  drops below the detection threshold. When the gate voltage  $V_{CRES}$  is applied from an external source,  $V_{CRES} = 7.5\text{ V}$ .
10.  $I_O = 1.0\text{ A}$  source + sink.
11. Input logic signal not present.

## DYNAMIC ELECTRICAL CHARACTERISTICS

Characteristics noted under conditions  $T_A = 25^\circ\text{C}$ ,  $V_{DD} = V_M = 5.0\text{ V}$ ,  $\text{GND} = 0\text{ V}$  unless otherwise noted. Typical values noted reflect the approximate parameter mean at  $T_A = 25^\circ\text{C}$  under nominal conditions unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
<b>INPUT (IN1, IN2, EN1, EN2)</b>					
Pulse Input Frequency	$f_{IN}$	–	–	200	kHz
Input Pulse Rise Time (Note 12)	$t_R$	–	–	1.0 (Note 13)	$\mu\text{s}$
Input Pulse Fall Time (Note 14)	$t_F$	–	–	1.0 (Note 13)	$\mu\text{s}$

## OUTPUT

Propagation Delay Time					$\mu\text{s}$
Turn-ON Time	$t_{PLH}$	–	0.1	0.5	
Turn-OFF Time	$t_{PHL}$	–	0.1	0.5	
Charge Pump Wake-Up Time (Note 15)	$t_{VGON}$	–	0.1	3.0	ms
Low-Voltage Detection Time	$t_{V_{DD}DET}$	–	–	10	ms

### Notes

12. Time is defined between 10% and 90%.
13. That is, the input waveform slope must be steeper than this.
14. Time is defined between 90% and 10%.
15. When  $C1 = C2 = C3 = 0.1\ \mu\text{F}$ .

Timing Diagrams

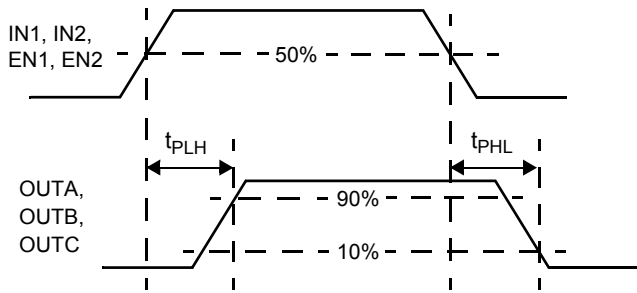


Figure 2.  $t_{PLH}$ ,  $t_{PHL}$ , and  $t_{PZH}$  Timing

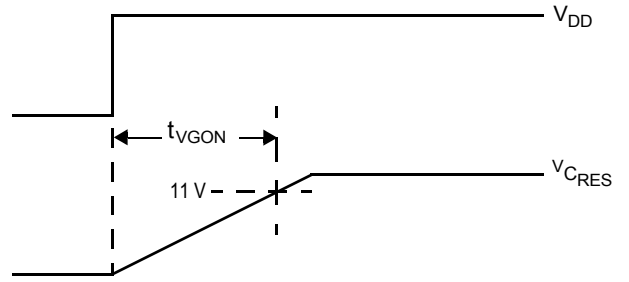


Figure 4. Charge Pump Timing

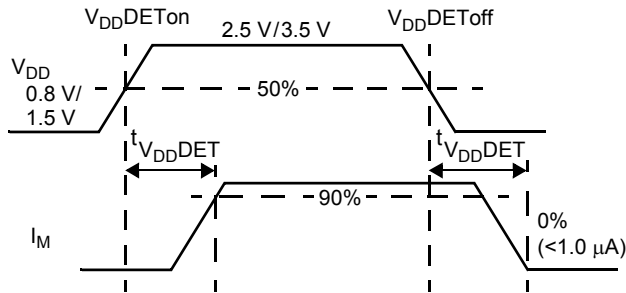


Figure 3. Low-Voltage Detection Timing

Table 1. Truth Table

INPUT				OUTPUT		
IN1	IN2	EN1	EN2	OUTA	OUTB	OUTC
<b>Shutdown Mode</b>						
X	X	L	L	Z	Z	Z
<b>Channel 1 (A–B) Driving Mode</b>						
H	H	H	L	L	L	Z
H	L	H	L	H	L	Z
L	H	H	L	L	H	Z
L	L	H	L	Z	Z	Z
<b>Channel 2 (B–C) Driving Mode</b>						
H	H	L	H	Z	L	L
H	L	L	H	Z	H	L
L	H	L	H	Z	L	H
L	L	L	H	Z	Z	Z
<b>Half-Bridge (C) Driving Mode</b>						
H	H	H	H	Z	Z	Z
H	L	H	H	Z	Z	H
L	H	H	H	Z	Z	L
L	L	H	H	Z	Z	Z

H = High.  
 L = Low.  
 Z = High impedance.  
 X = Don't care.



## SYSTEM/APPLICATION INFORMATION

### INTRODUCTION

The 17517 is a triple totem-pole output H-Bridge power IC designed to drive small dc motors used in portable electronics. The 17517 can operate efficiently with supply voltages as low as 2.0 V to as high as 6.8 V, and provide continuous motor drive currents of 1.0 A while handling peak currents up to 3.0 A. It is easily interfaced to low cost MCUs via parallel 3.0 V- or 5.0 V-compatible logic. The device can be pulse width modulated (PWM-ed) at up to 200 kHz. The 17517 can drive two motors in two directions one at a time; or it can drive one motor in two directions and one solenoid with synchronous rectification of freewheeling currents one at a time. Two-motor operation is accomplished by hooking one motor between OUTA and OUTB, and the other motor between OUTB and OUTC. Motor + solenoid operation is accomplished by hooking a motor

between OUTA and OUTB and placing a solenoid between OUTC and GND. [Table 1, Truth Table](#), page 8, describes the operating states versus the input conditions.

As shown in [Figure 1, 17517 Simplified Internal Block Diagram](#), page 2, the 17517 is a monolithic triple totem-pole output bridge with built-in charge pump circuitry. Each of the six MOSFETs forming the triple totem-pole output has an  $R_{DS(ON)}$  of  $\leq 0.6 \Omega$  (guaranteed by design). The IC has an integrated charge pump and level shifter (for gate drive voltages). Additionally, the IC has a built-in shoot-through current protection circuit and undervoltage lockout function. This IC has four operating modes: Forward, Reverse, Brake, and Tri-States (High Impedance).

### FUNCTIONAL TERMINAL DESCRIPTION

#### OUTA, OUTB, and OUTC

These terminals provide the connection to the internal power MOSFET triple-totem-pole H-bridge of the IC.

#### GND

Power and signal ground terminal.

#### C<sub>RES</sub>

This terminal provides the connection for the external reservoir capacitor (output of the charge pump). Alternatively, this terminal can also be used as an input to supply gate-drive voltage from an external source via a series current-limiting resistor.

The voltage at the C<sub>RES</sub> terminal will be approximately three times the V<sub>DD</sub> voltage, as the internal charge pump utilizes a voltage tripler circuit. The V<sub>DDRES</sub> voltage is used by the IC to supply gate drive for the internal power MOSFETs.

#### VM

The two VM terminals carry the main supply voltage and current into the power sections of the IC. This supply then becomes controlled and/or modulated by the IC as it delivers the power to the load attached between OUTA and OUTB.

The VM terminals must be connected together on the printed circuit board with as short as possible traces offering as low impedance as possible between terminals.

#### IN1, IN2, EN1, and EN2

These terminals are input control terminals used to control the outputs. These terminals are 3.0 V/5.0 V CMOS-compatible inputs with hysteresis. These terminals work together to control OUTA, OUTB, and OUTC (refer to [Table 1, Truth Table](#)).

#### C1L and C1H, C2L and C2H

These two pairs of terminals, the C1L and C1H and the C2L and C2H, connect to the external bucket capacitors required by the internal charge pump. The typical value for the bucket capacitors is 0.1  $\mu$ F.

#### V<sub>DD</sub>

This terminal carries the logic supply voltage and current into the logic sections of the IC. V<sub>DD</sub> has an undervoltage threshold. If the supply voltage drops below the undervoltage threshold, the output power stage switches to a tri-state condition. When the supply voltage returns to a level that is above the threshold, the power stage automatically resumes normal operation according to the established condition of the input terminals.

## APPLICATIONS

### Typical Application

Figure 5 shows a typical application for the 17517. When applying the gate voltage to the C<sub>RES</sub> terminal from an external

source, be sure to connect it via a resistor equal to, or greater than,  $R_G = V_{C_{RES}}/0.02 \Omega$ .

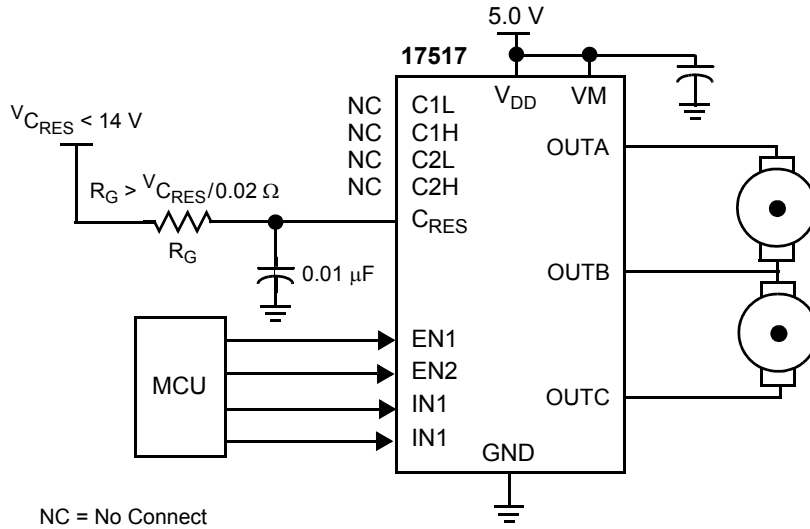


Figure 5. 17517 Typical Application Diagram

### CEMF Snubbing Techniques

Care must be taken to protect the IC from potentially damaging CEMF spikes induced when commutating currents in inductive loads. Typical practice is to provide snubbing of voltage transients by placing a capacitor or zener at the supply terminal (VM) (see Figure 6).

### PCB Layout

When designing the printed circuit board (pcb), connect sufficient capacitance between power supply and ground terminals to ensure proper filtering from transients. For all high-current paths, use wide copper traces and shortest possible distances.

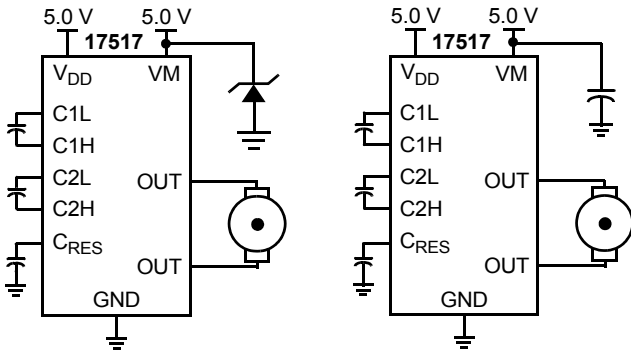
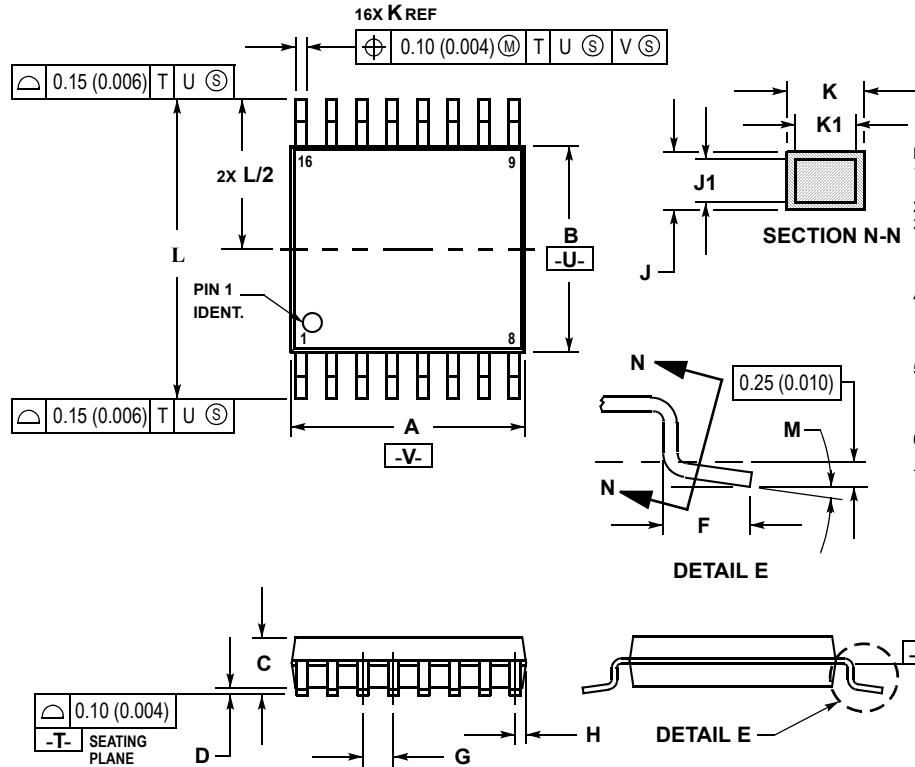


Figure 6. CEMF Snubbing Techniques

PACKAGE DIMENSIONS

DTB SUFFIX  
16-LEAD TSSOP  
PLASTIC PACKAGE  
CASE 948F-01  
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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